

Attorney Docket No.: NECW 18.159

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor: Atsushi NISHIZAWA

Serial No.: 09/751,979

Filed: December 29, 2000

Title: **MANUFACTURING METHOD OF SEMICONDUCTOR
INTEGRATED CIRCUIT INCLUDING SIMULTANEOUS
FORMATION OF VIA HOLE REACHING METAL WIRING
AND CONCAVE GROOVE IN INTERLAYER FILM AND
SEMICONDUCTOR INTEGRATED CIRCUIT MANUFACTURED
WITH THE MANUFACTURING METHOD**

Examiner: George A. Goudreau

Group Art Unit: 1763

Assistant Commission for Patents
Washington, D.C. 20231

CHANGE IN CORRESPONDENCE ADDRESS

FAX RECEIVED

NOV 19 2002

GROUP 1700

SIR:

It is respectfully requested that any future correspondence regarding the above-referenced application be directed to Applicant's attorneys (previously appointed) at the following new correspondence address:

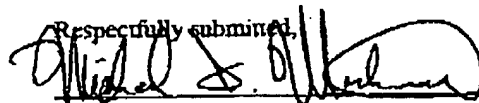
Katten Muchin Zavis Rosenman
575 Madison Avenue
New York, New York 10022
Phone: (212) 940-8800
Fax: (212) 940-8986 or (212) 940-8987

Any inquiries regarding this change in address may be directed to the Applicant's undersigned attorney at the above-referenced telephone numbers.

Our CUSTOMER NUMBER 026304 remains the same.

EVO96420885US

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DOCKET NO.: NECW 18.159

Respectfully submitted,

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